DRV3205-Q1 Three-Phase Automotive Gate Driver With Three Integrated Current Shunt Amplifiers and Enhanced Protection, Diagnostics, and Monitoring

1 Features

- AEC-Q100 Qualified for Automotive Applications:
  - Device Temperature Grade 1: –40°C to +125°C Ambient Operating Temperature
- Three-Phase Bridge Driver for Motor Control
- Suitable for 12-V and 24-V Applications
- Three Integrated High-Accuracy Current Sense Amplifiers
- Integrated Boost Converter, Gate Drive to 4.75 V
- Drives 6 Separate N-Channel Power MOSFETs
- Strong 1-A Gate Drive for High-Current FETs
- Programmable Dead Time
- PWM Frequency up to 20 kHz
- Supports 100% Duty Cycle Operation
- Short-Circuit Protection
  - VDS-Monitoring (Adjustable Detection Level)
  - Shunt Current Limit (Adjustable Detection Level)
- Overvoltage and Undervoltage Protection
- Overtemperature Warning and Shut Down
- Sophisticated Failure Detection and Handling Through SPI
- System Supervision
  - Q&A Watchdog
  - I/O Supply Monitoring
  - ADREF Monitoring
- Programmable Internal Fault Diagnostics
- Sleep Mode Function
- Thermally-Enhanced 48-Pin HTQFP PowerPAD™ IC Package (7-mm × 7-mm Body)

2 Applications

- **Automotive Motor-Control Applications**
  - Electrical Power Steering (EPS, EHPS)
  - Electrical Brake and Brake Assist
  - Transmission
  - Pumps
- **Industrial Motor-Control Applications**

3 Description

The DRV3205-Q1 bridge driver is dedicated to automotive three-phase brushless DC motor control applications. The device provides six dedicated drivers for standard-level N-channel MOSFET transistors. A boost converter with an integrated FET provides the overdrive voltage, allowing full control on the power stages even for low battery voltage down to 4.75 V. The strong driver strength is suitable for high-current applications and programmable to limit peak output current.

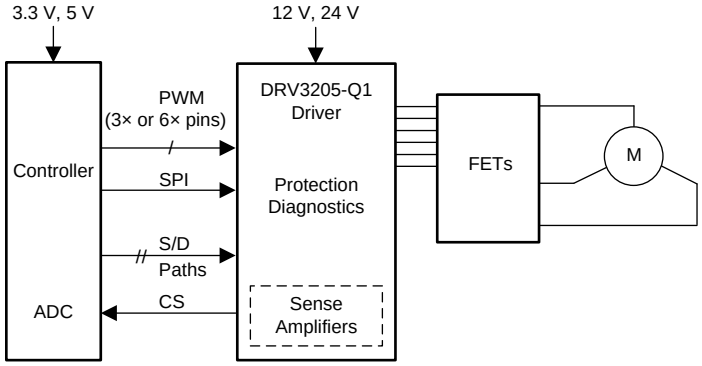
The device incorporates robust FET protection and system monitoring functions like a Q&A watchdog and voltage monitors for I/O supplies and ADC reference voltages. Integrated internal diagnostic functions can be accessed and programmed through an SPI interface.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
DRV3205-Q1	HTQFP (48)	7.00 mm × 7.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Typical Application Diagram



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (November 2016) to Revision E — **Page**

- Added the propagation delay graphs to the *Typical Characteristics* section ... 15
- Changed the note on the *Single 8-Bit SPI Frame/Transfer* figure ... 17
- Updated the *Typical Application Diagram* figure ... 22

Changes from Revision C (October 2016) to Revision D — **Page**

- Changed the maximum value for the RVSET resistor error detection parameter (4.4.31) from 1.5 to 1.4 kΩ in the *Electrical Characteristics* table ... 10
- Changed the units and symbol for the RVSET output voltage parameter (4.4.32–4.4.34), and fixed duplicate position number for T_J = 25°C and 125°C in the *Electrical Characteristics* table ... 10
- Added characterization note to parameters 5.7 and 5.29 through 5.30e in the *Electrical Characteristics* table ... 11
- Deleted the VS voltage range test condition from the boost output voltage parameter (6.1) in the *Electrical Characteristics* table ... 12
- Added new test condition to the switching frequency parameter (6.3) and add new values for switching frequency at V_S < 6 (6.31) in the *Electrical Characteristics* table ... 12
- Changed the maximum value for the input pulldown resistor at EN pin parameter (7.4) from 300 to 360 kΩ in the *Electrical Characteristics* table ... 12
- Changed the position number for the output high and low voltage 2 parameters in the *Electrical Characteristics* table ... 12
- Added characterization note to parameters 13.2 through 13.11 in the *Serial Peripheral Interface Timing Requirements* table ... 14

Changes from Revision B (October 2016) to Revision C — **Page**

- Clarified the temperature for the BOOST pin quiescent current parameters (3.6B and 3.6C) and added new temperature condition (3.62B and 3.61C) in the *Recommended Operating Conditions* table ... 7
- Deleted the maximum value for the input hysteresis parameters (7.3 and 7.3A) in the *Electrical Characteristics* table ... 12
- Changed the values for the input pullup resistance parameter (7.5) in the *Electrical Characteristics* table ... 12

Changes from Revision A (October 2016) to Revision B **Page**

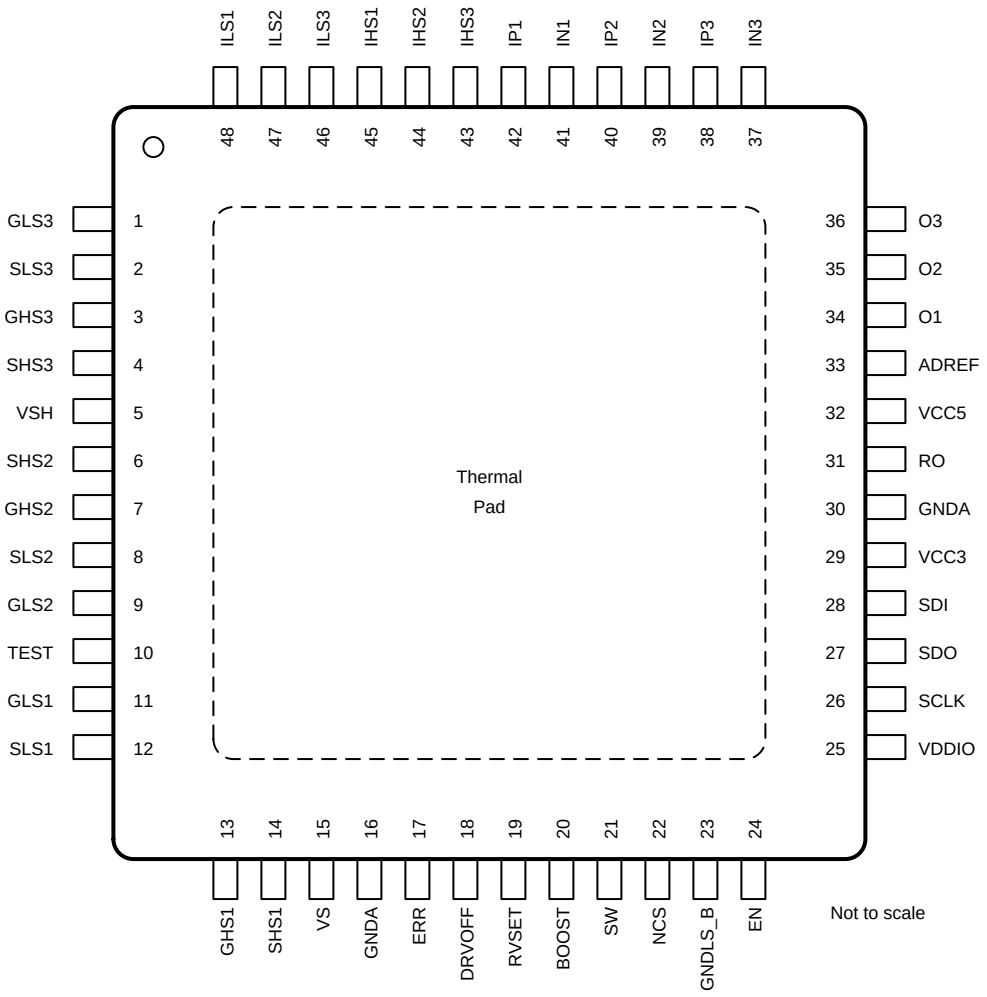
- Changed AEC-Q1100 to AEC-Q100 in the *Features* section 1
- Changed the maximum value for the VCC5 and VCC3 short-to-ground current from 70 to 80 mA in the *Absolute Maximum Ratings* table 6
- Changed the minimum value for the high-side/low-side driver shutdown current parameter from 7 to 2 mA in the *Electrical Characteristics* table 11

Changes from Original (September 2016) to Revision A **Page**

- Changed the device status from *Product Preview* to *Production Data* 1

5 Pin Configuration and Functions

PHP PowerPAD™ Package
48-Pin HTQFP
Top View



Pin Functions

PIN		TYPE(1)	DESCRIPTION
NO.	NAME		
1	GLS3	PWR	Gate low-side 3, connected to gate of external power MOSFET.
2	SLS3	PWR	Source low-side 3, connected to external power MOSFET for gate discharge and VDS monitoring.
3	GHS3	PWR	Gate high-side 3, connected to gate of external power MOSFET.
4	SHS3	PWR	Source high-side 3, connected to external power MOSFET for gate discharge and VDS monitoring.
5	VSH	HVI_A	Sense high-side, sensing VS connection of the external power MOSFETs for VDS monitoring.
6	SHS2	PWR	Source high-side 2, connected to external power MOSFET gate discharge and VDS monitoring.
7	GHS2	PWR	Gate high-side 2, connected to gate of external power MOSFET.
8	SLS2	PWR	Source low-side 2, connected to external power MOSFET for gate discharge and VDS monitoring.
9	GLS2	PWR	Gate low-side 2, connected to gate of external power MOSFET.
10	TEST	HVI_A	Test mode input, during normal application connected to ground.

(1) Description of pin type: GND = Ground; HVI_A = High-voltage input analog; HVI_D = High-voltage input digital; LVI_A = Low-voltage input analog; LVO_A = Low-voltage output analog; LVO_D = Low-voltage output digital; NC = No connect; PWR = Power output; Supply = Supply input

Pin Functions (continued)

PIN		TYPE(1)	DESCRIPTION
NO.	NAME		
11	GLS1	PWR	Gate low-side 1, connected to gate of external power MOSFET.
12	SLS1	PWR	Source low-side 1, connected to external power MOSFET for gate discharge and VDS monitoring.
13	GHS1	PWR	Gate high-side 1, connected to gate of external power MOS transistor.
14	SHS1	PWR	Source high-side 1, connected to external power MOS transistor for gate discharge and VDS.
15	VS	Supply	Power-supply voltage (externally protected against reverse battery connection).
16	GNDA	GND	Analog ground.
17	ERR	LVO_D	Error (low active), Error pin to indicate detected error.
18	DRVOFF	HVI_D	Driver OFF (high active), secondary bridge driver disable.
19	RVSET	HVI_A	VDDIO / ADREF OV/UV configuration resister.
20	BOOST	Supply	Boost output voltage, used as supply for the gate drivers.
21	SW	PWR	Boost converter switching node connected to external coil and external diode.
22	NCS	HVI_D	SPI chip select.
23	GNDLS_B	GND	Boost GND to set current limit. Boost switching current goes through this pin through external resistor to ground.
24	EN	HVI_D	Enable (high active) of the device.
25	VDDIO	Supply	I/O supply voltage, defines the interface voltage of digital I/O, for example, SPI.
26	SCLK	HVI_D	SPI clock.
27	SDO	LVO_D	SPI data output.
28	SDI	HVI_D	SPI data input.
29	VCC3	LVO_A	VCC3 regulator, for internal use only. TI recommends an external decoupling capacitor of 0.1 µF. External load < 100 µA.
30	GNDA	GND	Analog ground.
31	RO	LVO_A	Analog output.
32	VCC5	LVO_A	VCC5 regulator, for internal use only. Recommended external decoupling capacitor 1 µF. External load < 100 µA.
33	ADREF	LVI_A	ADC reference of MCU, used as maximum voltage clamp for O1 to O3.
34	O1	LVO_A	Output current sense amplifier 1.
35	O2	LVO_A	Output current sense amplifier 2.
36	O3	LVO_A	Output current sense amplifier 3.
37	IN3	LVI_A	Current sense negative input 3.
38	IP3	LVI_A	Current sense positive input 3.
39	IN2	LVI_A	Current sense input N 2.
40	IP2	LVI_A	Current sense input P 2.
41	IN1	LVI_A	Current sense input N 1.
42	IP1	LVI_A	Current sense input P 1.
43	IHS3	HVI_D	High-side input 3, digital input to drive the HS3.
44	IHS2	HVI_D	Input HS 2, digital input to drive the HS2.
45	IHS1	HVI_D	Input HS 1, digital input to drive the HS1.
46	ILS3	HVI_D	Low-side input 3, digital input to drive the LS3.
47	ILS2	HVI_D	Input LS 2, digital input to drive the LS2.
48	ILS1	HVI_D	Input LS 1, digital input to drive the LS1.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)[1][2]

POS				MIN	MAX	UNIT
2.1	VS, VSH	DC voltage		–0.3	60	V
2.1a	VS	DC voltage	Negative voltages with minimum serial resistor 5 Ω, T_A = 25°C	–5		V
2.1b	VSH	DC voltage	Negative voltages with minimum serial resistor 10 Ω, T_A = 25°C	–5		V
2.1c	VS	DC voltage	Negative voltages with minimum serial resistor 5 Ω, T_A = 105°C	–2.5		V
2.1d	VSH	DC voltage	Negative voltages with minimum serial resistor 10 Ω, T_A = 105°C	–2.5		V
2.2A	GHSx	Gate high-side voltage		–9	70	V
2.2B	SHSx	Source high-side voltage		–9	70	V
2.3	GHSx-SHSx	Gate-source high-side voltage difference	Externally driven, internal limited, see position 5.4 in *Electrical Characteristics*	–0.3	15	V
2.4	GLSx	Gate low-side voltage		–9	20	V
2.5	SLSx	Source low-side voltage		–9	7	V
2.6	GLSx-SLSx	Gate-source low-side voltage difference	Externally driven, internal limited, see position 5.5 in *Electrical Characteristics*	–0.3	15	V
2.7	BOOST, SW	Boost converter		–0.3	70	V
2.8	INx, IPx	Current sense input voltage		–9	7	V
2.8A	INx, IPx	Current sense input current	Clamping current	–5	5	mA
2.8C	Ox	Current sense output voltage		–0.3	ADREF +0.3	V
2.8D	Ox	Forced input current		–10	10	mA
2.9	VDDIO	Analog input voltage		–0.3	60	V
2.9a	ADREF	Analog input voltage		–0.3	60	V
2.10	ILSx,IHSx, EN, DRVOFF, SCLK, NCS, SDI	Digital input voltage		–0.3	60	V
2.11	RVSET	Analog input voltage		–0.3	60	V
2.13	GNDA, GNDLS_B	Difference between GNDA and GNDLS_B		–0.3	0.3	V
2.20		Maximum slew rate of SHSx pins, SR_{SHS}		–250	250	V/µs
2.21	ERR, SDO, RO	Analog and digital output voltages		–0.3	6	V
2.21 A	ERR, SDO, RO	Forced input/output current		–10	10	mA
2.22	TEST	Unused pins. Connect to GND.		–0.3	0.3	V
2.24	VCC5	Internal supply voltage		–0.3	6	V
2.24 A		Short-to-ground current, I_{VCC5}[3]	Internal current limit		80	mA
2.25	VCC3	Internal supply voltage		–0.3	3.6	V
2.26		Short-to-ground current, I_{VCC3}	Limited by VCC5		80	mA
2.27		Driver FET total gate charge (per FET), Q_{gmax}	VS = 12 V, f_{PWM} = 20 kHz, 6 FETs ON/OFF per PWM cycle		200[4]	nC
2.28			VS = 24 V, f_{PWM} = 20 kHz, 6 FETs ON/OFF per PWM cycle		100[4]	nC

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network ground terminal, unless specified otherwise.
(3) I_{VCC5} is not specifying VCC5 output current capability for external load. The allowed external load on VCC5 is specified at position 3.18 in *Recommended Operating Conditions*.
(4) The maximum value also depends on PCB thermal design, modulation scheme, and motor operation time.

Absolute Maximum Ratings (continued)

over operating free-air temperature range (unless otherwise noted)(1)(2)

POS			MIN	MAX	UNIT
2.14		Operating virtual junction temperature, T_J	–40	150	°C
2.15		Storage temperature, T_{stg}	–55	165	°C

6.2 ESD Ratings

POS				VALUE	UNIT
2.17	$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per AEC Q100-002(1)	All pins	±2000	V
			Pins 4, 6, and 14	±4000	
2.18		Charged-device model (CDM), per AEC Q100-011	All pins	±500	
2.19			Corner pins (1, 12, 13, 24, 25, 36, 37, and 48)	±750	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

POS				MIN	NOM	MAX	UNIT
3.1	VS	Supply voltage, normal voltage operation	Full device functionality. Operation at VS = 4.75 V only when coming from higher VS. Minimum VS for startup = 4.85 V	4.75		40	V
3.2	VSLO	Supply voltage, logic operation	Logic functional (during battery cranking after coming from full device functionality)	4		40	V
3.3	VDDIO	Supply voltage for digital I/Os		2.97		5.5	V
3.4	D	Duty cycle of bridge drivers		0%		100%	
3.5	f_{PWM}	PWM switching frequency		0		22(1)	kHz
3.6A	I_{VSn}	VS quiescent current normal operation (boost converter enabled, drivers not switching)	Boost converter enabled, see and for SHSx/SLSx connections. EN_GDBIAS = 1			22	mA
3.61A	I_{VSn}	VS quiescent current normal operation (boost converter enabled, drivers not switching)	Boost converter enabled, see and for SHSx/SLSx connections. EN_GDBIAS = 0			22.3	mA
3.6B	I_{BOOSTn}	BOOST pin quiescent current normal operation (drivers not switching)	4.75 V < VS < 20 V, T_A = 25°C to 125°C			9	mA
3.62B			4.75 V < VS < 20 V, T_A = –40°C			10	mA
3.61B	I_{VSn}	VS quiescent additional current normal operation because of RVSET thermal voltage output enabled (boost converter enabled, drivers not switching)	THERMAL_RVSET_EN = 1			0.6	
3.6C	I_{BOOSTn}	BOOST pin quiescent current normal operation (drivers not switching)	20 < VS < 40 V, T_A = 25°C to 125°C			9.5	mA
3.61C			20 < VS < 40 V, T_A = –40°C			10.5	
3.6D	$I_{BOOST,sw}$	BOOST pin additional load current because of switching gate drivers	Excluding FET gate charge current. 20-kHz all gate drivers switching at the same time. EN_GDBIAS = 1			4	mA
3.61D	$I_{BOOST,sw}$	BOOST pin additional load current because of switching gate drivers	Excluding FET gate charge current. 20-kHz all gate drivers switching at the same time. EN_GDBIAS = 0			5.4	mA
3.75	I_{VSq_1}	VS quiescent current shutdown (sleep mode) 1	VS = 14 V, no operation, T_J < 25°C, EN = Low, total leakage current on all supply connected pins			20	µA
3.75a	I_{VSq_2}	VS quiescent current shutdown (sleep mode) 2	VS = 14 V, no operation, T_J < 85°C, EN = Low, total leakage current on all supply connected pins			30	µA
3.8	T_J	Junction temperature		–40		150	°C
3.9	T_A	Operating ambient free-air temperature	With proper thermal connection	–40		125	°C
3.11	V_{INx},V_{IPx}	Current sense input voltage	V_{IPx} – V_{Inx}, RO = 2.5 V GAIN = 12	–0.15		0.15	V
3.13	ADREF	Clamping voltage for current sense amplifier outputs O1/2/3		2.97		5.5	V
3.13a		Reserved					V

(1) Maximum PWM allowed also depends on maximum operating temperature, FET gate charge current, VS supply voltage, modulation scheme, and PCB thermal design.

Recommended Operating Conditions (continued)

POS				MIN	NOM	MAX	UNIT
3.13b		Reserved					V
3.14	VCC3	Internal supply voltage	VS > 4 V, external load current <100 µA, decoupling capacitor typical 0.1 µF	3(1)		3.3	V
3.15	I_{VCC3}	VCC3 output current	Intended for MCU ADC input	0		100	µA
3.16	C_{VCC3}	VCC3 decoupling capacitance		0.075	0.1	0.2	µF
3.17	VCC5	Internal supply voltage	VS > 6 V, external load current < 100 µA, decoupling capacitor typical 1 µF	5.15		5.45	V
3.18	I_{VCC5}	VCC5 output current	Intended for MCU ADC input	0		100	µA
3.19	C_{VCC5}	VCC5 decoupling capacitance		0.5	1	1.5	µF

6.4 Thermal Information

THERMAL METRIC(1)		DRV3205-Q1 PHP (HTQFP) 48 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	25.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	10.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	6	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	5.9	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	0.3	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report (SPRA953).

6.5 Electrical Characteristics

over operating temperature T_J = –40°C to 150°C and recommended operating conditions, VS = 4.75 V to 40 V(1), f_{PWM} < 20 kHz (unless otherwise noted)

POS	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
4.1	**CURRENT SENSE AMPLIFIER**						
4.2.1	V_{off1a}	Initial input offset of amplifiers	T_J = 25°C, ADREF = 5 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50		±1		mV
4.2.1a	V_{off1a}	Initial input offset of amplifiers	T_J = 25°C, ADREF = 3.3 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50		±1		mV
4.2.2	V_{off1b}	Temperature and aging offset(2)	ADREF = 5 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50		±1		mV
4.2.2a	V_{off1b}	Temperature and aging offset(2)	ADREF = 3.3 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50		±1		mV
4.2.3	V_{com1}(3)	Input common voltage range		–3		3	V
4.2.4	V_{Oa}	Nominal output voltage level, positive ox swing	Normal voltage operation, VS ≥ 5.75 V; 0.5-mA load current	ADREF – 0.5 + V_{oxm}			V
4.2.4a	V_{Oa}	Nominal output voltage level, negative ox swing	Normal voltage operation, VS ≥ 5.75 V; 0.5-mA load current			0.5	V
4.2.4b	V_{Oa}	Nominal output voltage level 2, positive ox swing	Normal voltage operation, VS ≥ 5.75 V; 10-µA load current	ADREF – 0.06 + V_{oxm}			V
4.2.4c	V_{Oa}	Nominal output voltage level 2, negative ox swing	Normal voltage operation, VS ≥ 5.75 V; 10-µA load current			0.09	V
4.2.5	V_{Ob}	Output voltage level during low voltage operation, positive ox swing	Low voltage operation, 4.75 V ≤ VS < 5.75 V; 0.5-mA load current	VS – 1.25; ADREF – 0.5 + V_{oxm}			V
4.2.5a	V_{Ob}	Output voltage level during low voltage operation, negative ox swing	Low voltage operation, 4.75 V ≤ VS < 5.75 V; 0.5-mA load current			0.5	V

(1) Product life time depends on VS voltage, PCB thermal design, modulation scheme, and motor operation time. The product is designed for 12-V and 24-V battery system.
(2) Ensured by characterization.
(3) ADREF / VDDIO overvoltage and undervoltage is set by RVSET.

Electrical Characteristics (continued)

over operating temperature T_J = –40°C to 150°C and recommended operating conditions, VS = 4.75 V to 40 V(1), f_{PWM} < 20 kHz (unless otherwise noted)

POS	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
4.2.5b	V_{Ob}	Output voltage level during low voltage operation 2, positive ox swing	Low voltage operation, 4.75 V ≤ VS < 5.75 V; 10-µA load current	VS – 0.75; ADREF – 0.06 + V_{oxm}			V
4.2.5c	V_{Ob}	Output voltage level during low voltage operation 2, negative ox swing	Low voltage operation, 4.75 V ≤ VS < 5.75 V; 10-µA load current			0.09	V
4.2.6	GBP	Gain bandwidth product GBP	0.5 V ≤ O1/2/3 ≤ 4.5 V, capacitor load = 25 pF, specified by design.	5			MHz
4.2.8	G1	Gain 1	SPI configurable, Normal voltage operation, VS ≥ 5.75 V; 0.5-mA load current	7.896	8	8.096	V/V
4.2.9	G2	Gain 2	SPI configurable, Normal voltage operation, VS ≥ 5.75 V; 0.5-mA load current	11.856	12	12.144	V/V
4.2.10	G3	Gain 3	SPI configurable, Normal voltage operation, VS ≥ 5.75 V; 0.5-mA load current	15.808	16	16.192	V/V
4.2.11	G4	Gain 4	SPI configurable, Normal voltage operation, VS ≥ 5.75 V; 0.5-mA load current	31.616	32	32.384	V/V
4.2.12	$PSRR_{o123}$	Power supply rejection ratio at DC	VS to O1/2/3 decoupling capacitor typical 1 µF on VCC5 / 0.1-µF VCC3 at DC Specified by design, capacitor load = 25 pF RO = 2.5 V, ADREF = 5 V, gain = 16, dVS / dOx dVCC5 / dOx	60	80		dB
4.2.12a	$CMRR_{o123}$	Common mode rejection ratio at DC	Specified by design, capacitor load = 25 pF RO = 2.5 V, ADREF = 5 V, gain = 1, VS = 12 V	70	80		dB
4.2.12b	CMG_{o123}	Common mode gain at 500 kHz	Specified by design, capacitor load = 25 pF RO = 2.5 V, ADREF = 5 V, gain = 16			–29	dB
4.2.12c	CMG_{o123}	Common mode gain peak	Specified by design, capacitor load = 25 pF RO = 2.5 V, ADREF = 5 V, gain = 16			–15	dB
4.2.13	Iinamp	Inx, IPx input bias current	VCM (input common mode voltage) = ±3 V, RSHUNT_MODE[1:0] = 11		50	90	µA
4.2.13	Iinamp2	Inx, IPx input bias current	VCM (input common mode voltage) = ±3 V, RSHUNT_MODE[1:0] = 2'b000110		60	90	µA
4.2.14	$Tsettle_{O123}$	Ox settling time to withing ±2% of final value	Specified by design, capacitor load = 25 pF, RO = 2.5 V, ADREF = 5 V, gain = 16, 0.5 V ≤ O1/2/3 ≤ 4.5 V			0.8	µs
4.2.15	Iinampd	Inx, IPx Input bias differential current	VCM = ±3 V $I_{IPx-INx}$, IPx-INx = 0 V, RSHUNT_MODE[1:0] = 11	–1.2		1.2	µA
4.2.16	Rinam	Inx, IPx Input resistance	VCM = ±3 V	9	12	15	kΩ
4.2.12d	$PSRR3_{o123}$	Power supply rejection ratio at DC	VS to O1/2/3 decoupling capacitor typical 1 µF on VCC5 / 0.1-µF VCC3 at DC specified by design, capacitor load = 25 pF RO = 1.65 V ADREF = 3.3 V, gain = 16, dVS / dOx dVCC5 / dOx	70	80		dB
4.2.12e	$CMRR_{3o123}$	Common mode rejection ratio at DC	Specified by design, capacitor load = 25 pF RO = 1.65 V ADREF = 3.3 V, gain = 16 VS = 12 V	70	80		dB
4.2.12f	$CMG3_{o123}$	Common mode gain at 500 kHz	Specified by design, capacitor load = 25 pF RO = 1.65 V ADREF = 3.3 V, gain = 16			–29	dB
4.2.12g	$CMG3_{o123}$	Common mode gain peak	Specified by design, capacitor load = 25 pF RO = 1.65 V ADREF = 3.3 V, gain = 16			–15	dB

Electrical Characteristics (continued)

over operating temperature T_J = –40°C to 150°C and recommended operating conditions, VS = 4.75 V to 40 V(1), f_{PWM} < 20 kHz (unless otherwise noted)

POS	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
4.3	**SHIFT BUFFER**						
4.3.2	VRO	Shift output voltage range	ADREF = 5 V	0.1 × ADREF		0.5 × ADREF	V
4.3.3	VR_{offset}	Shift voltage offset (with respect to RO)	ADREF = 5 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50, I_{load} = internal load		±1.7		mV
4.3.3a			RO_CFG [4:0] = 5'b00100: ADREF × 5 / 50-5'b10111: ADREF × 24 / 50		±4		mV
4.3.3b	VR_{offset}	Shift voltage offset (with respect to ADREF (3.3 V) × 25 / 50 (RO_CFG [4:0] = 5'b11000))	ADREF = 3.3 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50, I_{load} = internal load		±1.7		mV
4.3.4	C_{RO}	RO output load capacitance range		0		150	pF
4.3.5	I_{RO}	Shift output current capability	ADREF = 5 V, RO_CFG [4:0] = 5'b11000: ADREF × 25 / 50	–5		5	mA
4.3.6			RO_CFG [4:0] = 5'b00100: ADREF × 5 / 50-5'b10111: ADREF × 24 / 50	–1		1	mA
4.3.7	$T_{dgadref}$	ADREF UV/ OV detection deglitch time		3	5	7	µs
4.3.8	$PSRR_{RO}$	Power supply rejection ratio at DC	Decoupling capacitor typical 1 µF on VCC5 / 0.1 µF VCC3 at DC. Specified by design, capacitor load = 25 pF RO = 2.5 V ADREF = 5 V, Gain = 16, dVS / d_{RO} dVCC5 / d_{RO}	70	80		dB
4.4.9	$t_{dgadref}$	ADREF UV/OV detection deglitch time		3	5	7	µs
4.4	**ADREF / VDDIO**						
4.4.1	V_{oxm}	Tolerance of ADREF voltage clamp	Relative to ADREF 5.75 V ≤ VS	–0.1	0.03	0.25	V
4.4.2	V_{oxos}	Overshoot of O1/2/3 over ADREF	Ox-ADREF; for <1 µs; specified by design			1.2	V
4.4.3	I_{ADREF}	Bias current for voltage clamping circuit	ADREF = 3.3 V, pin to ground			300	µA
4.4.4	$V_{ovadref}$	Overvoltage threshold	ADREF: 3.3-V setting by RVSET resistor	3.696	3.795	3.894	V
4.4.4a			ADREF: 5-V setting by RVSET resistor	5.6	5.75	5.9	V
4.4.5	$V_{uvadref}$	Undervoltage threshold	ADREF: 3.3-V setting by RVSET resistor	2.706	2.805	2.904	V
4.4.5a			ADREF: 5-V setting by RVSET resistor	4.1	4.25	4.4	V
4.4.7	$V_{ovvddio}$	Overvoltage threshold	VDDIO: 3.3-V setting by RVSET resistor	3.696	3.795	3.894	V
4.4.7a			VDDIO: 5-V setting by RVSET resistor	5.6	5.75	5.9	V
4.4.8	$V_{uvvddio}$	Undervoltage threshold	VDDIO: 3.3-V setting by RVSET resistor	2.706	2.805	2.904	V
4.4.8a			VDDIO: 5-V setting by RVSET resistor	4.1	4.25	4.4	V
4.4.10	R_{vset33}	VDDIO = 3.3 V / ADREF = 3.3-V mode	STAT6 bit[3:0] = 4'b0001	135	150	165	kΩ
4.4.11	R_{vset53}	VDDIO = 5 V / ADREF = 3.3-V mode	STAT6 bit[3:0] = 4'b0100	46	51	56.5	kΩ
4.4.12	R_{vset35}	VDDIO = 3.3 V / ADREF = 5-V mode	STAT6 bit[3:0] = 4'b1000	13.5	15	16.5	kΩ
4.4.13	R_{vset55}	VDDIO = 5 V / ADREF = 5-V mode	STAT6 bit[3:0] = 4'b0010	4.6	5.1	5.65	kΩ
4.4.30	$R_{vsetopen}$	RVSET resistor error detection		650			kΩ
4.4.31	$R_{vsetshort}$	RVSET resistor error detection				1.4	kΩ
4.4.32	$V_{rvsettjn40}$	RVSET output voltage	–40°C T_J, THERMAL_RVSET_EN = 1	1.67	1.745	1.82	V
4.4.33	$V_{rvsettj25}$		25°C T_J, THERMAL_RVSET_EN = 1	1.445	1.535	1.625	
4.4.34	$V_{rvsettj125}$		125°C T_J, THERMAL_RVSET_EN = 1	1.085	1.195	1.305	

Electrical Characteristics (continued)

over operating temperature T_J = –40°C to 150°C and recommended operating conditions, VS = 4.75 V to 40 V(1), f_{PWM} < 20 kHz (unless otherwise noted)

POS	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
	VCC3 / VCC5 REGULATORS						
4.4.14	VCC3	VCC3 regulator output voltage	VS > 4 V	3	3.15	3.3	V
4.4.15	$VCC3_{UV}$	VCC3 regulator undervoltage threshold	VS > 4 V	2.7	2.85	3	V
4.4.16	$VCC3_{OV}$(3)	VCC3 regulator overvoltage threshold	VS > 4 V	3.3	3.45	3.6	V
4.4.17	VCC5_1	VCC5 regulator output voltage 1	VS > 6 V	5.15	5.3	5.45	V
4.4.18	VCC5_2	VCC5 regulator output voltage 2	6 V > VS > 4.75 V	4.6		5.45	V
4.4.19	$VCC5_{UV}$	VCC5 regulator undervoltage threshold	VS > 4.75 V	4.3		4.6	V
4.4.20	$VCC5_{OV}$	VCC5 regulator overvoltage threshold	VS > 4.75 V	5.45	5.6	5.75	V
5.	**GATE DRIVER**						
5.1	$V_{GS,low}$	Gate-source voltage low, high-side/low-side driver	Active pulldown, I_{load} = –2 mA	0		0.2	V
5.2	R_{GSp}	Passive gate-source resistance	Vgs ≤ 200 mV	110	220	330	kΩ
5.3	R_{GSsa}	Semi-active gate-source resistance	In sleep mode, V_{GS} > 2 V		2	4	kΩ
5.3b	I_{GSL01}	Low-side driver pullup/pulldown current	Gate driven low by gate driver, CURR1, 3 = 01, SPI configurable	TYP × 0.65	0.65	TYP × 1.35	A
5.3c	I_{GSL00}		Gate driven low by gate driver(3), CURR1, 3 = 00, SPI configurable	TYP × 0.1	0.15	TYP × 1.9	A
5.3d	I_{GSL10}		Gate driven low by gate driver, CURR1, 3 = 11, SPI configurable	TYP × 0.65	1.1	TYP × 1.35	A
5.3f	I_{GSH01}	High-side driver pullup/pulldown current	Gate driven low by gate driver, CURR0, 2 = 01, SPI configurable	TYP × 0.65	0.65	TYP × 1.35	A
5.3g	I_{GSH00}		Gate driven low by gate driver(3), CURR0, 2 = 00, SPI configurable	TYP × 0.1	0.15	TYP × 1.9	A
5.3h	I_{GSH11}		Gate driven low by gate driver, CURR0, 2 = 11, SPI configurable	TYP × 0.65	1.1	TYP × 1.35	A
5.3i	I_{GSHsd}	High-side/low-side driver shutdown current		2	30	70	mA
5.4	$V_{GS,HS,high}$	High-side output voltage	I_{load} = –2 mA; 4.75 V < VS < 40 V	9		13.4	V
5.5	$V_{GS,LS,high}$	Low-side output voltage	I_{load} = –2 mA	9		13.4	V
5.27	t_{Don}	Propagation on delay time(2)	After ILx/IHx rising edge, Cload = 10 nF, CURR1, 3 = 10, VGS = 1 V	100	200	350	ns
5.31	A_{dt}	Accuracy of dead time	If not disabled in CFG1	–15%		15%	
5.32	IHSxlk_1	Source leak current, total leakage current of source pins	EN = L, SHSx = 1.5 V, T_J < 125°C	–5		5	µA
5.32a	IHSxlk_2		EN = L, SHSx = 1.5 V, 125°C < T_J < 150°C	–40		40	µA
5.29	t_{Doff}	Propagation off delay time(2)	ILx/IHx falling edge to $V_{GS,LS,high}$($V_{GS,HS,high}$) – 1 V Ciss = 10 nF, CURR1,3 = 10,	100	200	350	ns
5.30	$t_{Doffdiff}$	Propagation off delay time difference(2)	LSx to LSy and HSx to HSy Cload = 10 nF, CURR1,3 = 10, $V_{GS,LS,high}$($V_{GS,HS,high}$) – 1 V			50	ns
5.30a	$t_{Don\_Doff\_diff}$	Difference between propagation on delay time and propagation off delay time(2)	For each gate driver in each channel: Cload = 10 nF, CURR1, 3 = 10, VGS = 1 V (rising), $V_{GS,LS,high}$($V_{GS,HS,high}$) – 1 V (falling)			150	ns
5.30c	t_{ENoff}	Propagation off (EN) deglitching time(2)	After falling edge on EN	2.5	6	12	µs
5.30d	t_{SD}	Time until gate drivers initiate shutdown(2)	After falling edge on EN		12	24	µs
5.30e	t_{SDDRV}	Time until gate drivers initiate shutdown(2)	After rising edge on DRVOFF			10	µs

Electrical Characteristics (continued)

over operating temperature T_J = –40°C to 150°C and recommended operating conditions, VS = 4.75 V to 40 V(1), f_{PWM} < 20 kHz (unless otherwise noted)

POS	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
6.	**BOOST CONVERTER**						
6.1	V_{BOOST}	Boost output voltage excluding switching ripple and response delay.	BOOST-VS voltage	14	15	16.5	V
6.1b	$V_{BOOSTOV}$	Boost output voltage overvoltage with respect GND		64	67.5	70	V
6.2	I_{BOOST}	Output current capability	External load current including external MOSFET gate charge current BOOST – VS > $V_{BOOSTUV}$	40			mA
6.3	f_{BOOST}	Switching frequency	BOOST – VS > $V_{BOOSTUV}$; ensured by characterization(4)	1.8	2.5	3	MHz
6.31			BOOST – VS > $V_{BOOSTUV}$; V_S < 6 V; ensured by characterization(4)	1.1		3	
6.4	$V_{BOOSTUV}$	Undervoltage shutdown level	BOOST-VS voltage	7		8	V
6.4a	$V_{BOOSTUV2}$	Undervoltage condition that device may enter RESET state	BOOST-GND voltage			10	V
6.5	t_{BCSD}	Filter time for undervoltage detection		5		6	µs
6.7	$V_{GNDLS\_B,off}$	Voltage at GNDLS_B pin at which boost FET switches off because of current limit		110	150	200	mV
6.7a	$t_{SW,off}$	Delay of the GNDLS_B current limit comparator	Specified by design			100	ns
6.8	$I_{SW,fail}$	Internal second-level current limit	GNDLS_B = 0 V	840		1600	mA
6.9	R_{dson_BSTfet}	R_{dson} resistance boost FET	VS ≥ 6 I_{SW} = $V_{GNDLS\_B,off}$ / 0.33 Ω	0.25		1.5	Ω
6.9a			VS < 6 I_{SW}= $V_{GNDLS\_B,off}$ / 0.33 Ω			2	Ω
7.	**DIGITAL INPUTS**						
7.1	INL	Input low threshold	All digital inputs NCS, DRVOFF, ILSx, IHSx, SDI			VDDIO × 0.3	V
7.1a	ENH	EN input high threshold	VS > 4 V	2.7			V
7.1b	ENL	EN input low threshold	VS > 4 V			0.7	V
7.2	INH	Input high threshold	All digital inputs NCS, DRVOFF, ILSx, IHSx, SDI	VDDIO × 0.7			V
7.3	Inhys	Input hysteresis	All digital inputs EN, NCS, DRVOFF, ILSx, IHSx, SDI, VDDIO = 5 V	0.3	0.4		V
7.3a	Inhys	Input hysteresis	All digital inputs EN, NCS, DRVOFF, ILSx, IHSx, SDI, VDDIO = 3.3 V	0.2	0.3		V
7.4	$R_{pd,EN}$	Input pulldown resistor at EN pin	EN	140	200	360	kΩ
7.4a	$t_{deg,ENon}$	Power-up time after EN pin high from sleep mode to active mode	ERR = L → H			5	ms
7.5	R_{pullup}	Input pullup resistance	NCS, DRVOFF	200	280	400	kΩ
7.6	$R_{pulldown}$	Input pulldown resistance	ILSx, IHSx, SDI , SCLK Input voltage = 0.1 V	100	140	200	kΩ
7.6a	$R_{pulldown}$	Input pulldown current	ILSx, IHSx, SDI, SCLK Input voltage = VDDIO	4		50	µA
8.	**DIGITAL OUTPUTS**						
8.1	OH1	Output high voltage 1	All digital outputs: SDO, I = ±2 mA; VDDIO in functional range(5)	VDDIO × 0.9			V
8.2	OL1	Output low voltage 1	All digital outputs: SDO, I = ±2 mA; VDDIO in functional range			VDDIO × 0.1	V
8.3	OH2	Output high voltage 2	ERR I = –0.2 mA; VDDIO in functional range	VDDIO × 0.9			V
8.4	OL2	Output low voltage 2	ERR I = +0.2 mA; VDDIO in functional range			VDDIO × 0.1	V
9.	**VDS / VGS / R_{SHUNT} MONITORING**						
9.1	V_{SCTH}	VDS short-circuit threshold range	If not disabled in CFG1	0.1		2	V

(4) During startup when BOOST-VS < VBOOSTUV , f_{BOOST} is typically 1.25 MHz.
(5) All digital outputs have a push-pull output stage between VDDIO and ground.

Electrical Characteristics (continued)

over operating temperature T_J = –40°C to 150°C and recommended operating conditions, VS = 4.75 V to 40 V(1), f_{PWM} < 20 kHz (unless otherwise noted)

POS	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
9.2	A_{vds}	Accuracy of VDS monitoring	0.1-V to 0.5-V threshold setting	–50		50	mV
			0.6-V to 2-V threshold setting	–10%		10%	
9.3	t_{VDS}	Detection filter time	Only rising edge of VDS comparators are filtered		5		µs
9.4	V_{gserr+_1}	VGS error detection 1	STAT7, IHSx (ILSx) = H	7		8.5	V
9.5	V_{gserr-}	VGS error detection	STAT7, IHSx (ILSx) = L			2	V
9.6	t_{VGS}	Detection filter time	CFG6[5:4]		1.0		µs
9.6a	t_{VGSm}	Detection mask time	CFG6[2:0]		2.5		µs
9.7	V_{SHUNT}	R_{SHUNT} shutdown threshold range	SPI configurable	75		540	mV
9.8	A_{VSHUNT}	Accuracy of R_{SHUNT} shutdown	75-mV to 165-mV setting	–18		18	mV
			180-mV to 540-mV setting	–10%		10%	
9.9	t_{VSHUNT}	Detection filter time			5		µs
10.	**THERMAL SHUTDOWN**						
10.1	T_{msd0}	Thermal recovery	Specified by characterization	130	153	178	°C
10.2	T_{msd1}	Thermal warning	Specified by characterization	140	165	190	°C
10.3	T_{msd2}	Thermal global reset	Specified by characterization	170	195	220	°C
10.4	T_{hmsd}	Thermal shutdown×2 hysteresis	Specified by characterization		40		°C
10.5	t_{TSD1}	Thermal warning filter time	Specified by characterization	40	45	50	µs
10.6	t_{TSD2}	Thermal shutdown×2 filter time	Specified by characterization	2.5	6	12	µs
12.	**VS MONITORING**						
12.1	$V_{VS,OVoff0}$	Overvoltage shutdown level range(6)	Programmable CFG5 mode1, 12-V/24-V mode	29		38	V
12.1a	$V_{VS,OVoff1}$	Overvoltage shutdown level(6)	29-V threshold setting	27.5	29	30.5	V
12.1b	$V_{VS,\ OVon1}$	Recovery level form overvoltage shutdown(6)	29-V threshold setting	26.5	28	29.5	V
12.1c	$V_{VS,OVoff2}$	Overvoltage shutdown level(6)	33-V threshold setting	32	33.5	35	V
12.1d	$V_{VS,\ OVon2}$	Recovery level form overvoltage shutdown(6)	33-V threshold setting	31	32.5	34	V
12.1e	$V_{VS,OVoff3}$	Overvoltage shutdown level(6)	38-V threshold setting	36.5	38	39.5	V
12.1f	$V_{VS,\ OVon3}$	Recovery level form overvoltage shutdown(6)	38-V threshold setting	35.5	37	38.5	V
12.2	$V_{VS,UVoff}$	Undervoltage shutdown level(6)	VS is falling from higher voltage than 4.75 V	4.5		4.75	V
12.2a	$V_{VS,UVon}$	Recovery level form undervoltage shutdown(6)	Minimum VS for device startup	4.6		4.85	V
12.3	$t_{VS,SHD}$	Filter time for overvoltage/undervoltage shutdown		5		6	µs

(6) *Shutdown* signifies *predriver shutdown*, not VCC3/VCC5 regulator shutdown.

6.6 Serial Peripheral Interface Timing Requirements

POS 13			MIN	NOM	MAX	UNIT
13.1	f_{SPI}	SPI clock (SCLK) frequency			4 (1)	MHz
13.2	t_{SPI}	SPI clock period (2)	250			ns
13.3	t_{high}	High time: SCLK logic high duration (2)	90			ns
13.4	t_{low}	Low time: SCLK logic low duration (2)	90			ns
13.5	t_{sucs}	Setup time NCS: time between falling edge of NCS and rising edge of SCLK (2)	t_{SPI} / 2			ns
13.6	t_{d1}	Delay time: time delay from falling edge of NCS to data valid at SDO (2)			60	ns
13.7	t_{susi}	Setup time at SDI: setup time of SDI before the rising edge of SCLK (2)	30			ns
13.8	t_{d2}	Delay time: time delay from falling edge of SCLK to data valid at SDO (2)	0		60	ns
13.9	t_{hcs}	Hold time: time between the falling edge of SCLK and rising edge of NCS (2)	45			ns
13.10	t_{hlcs}	SPI transfer inactive time (time between two transfers) (2)	250			ns
13.11	t_{tri}	Tri-state delay time: time between rising edge of NCS and SDO in tri-state (2)			30	ns

(1) The maximum SPI clock tolerance is ±10%.
(2) Ensured by characterization.

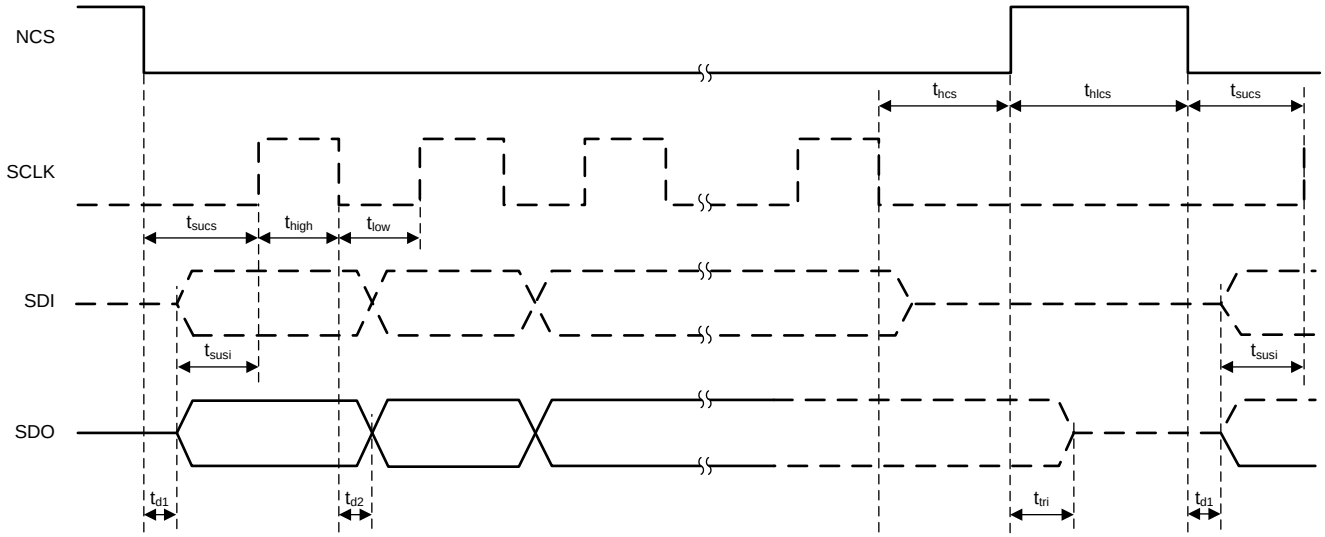


Figure 1. SPI Timing Parameters

6.7 Typical Characteristics

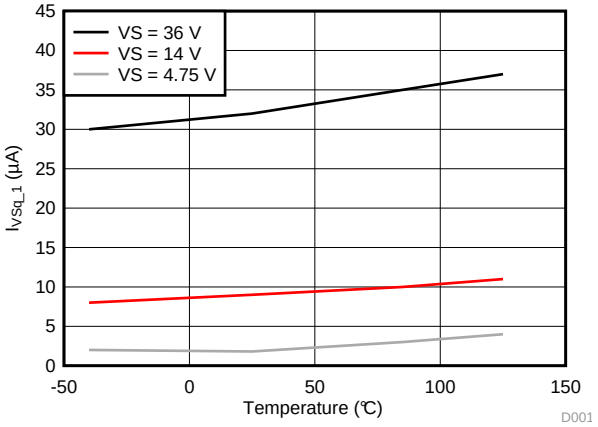


Figure 2. VS Quiescent Current Shutdown

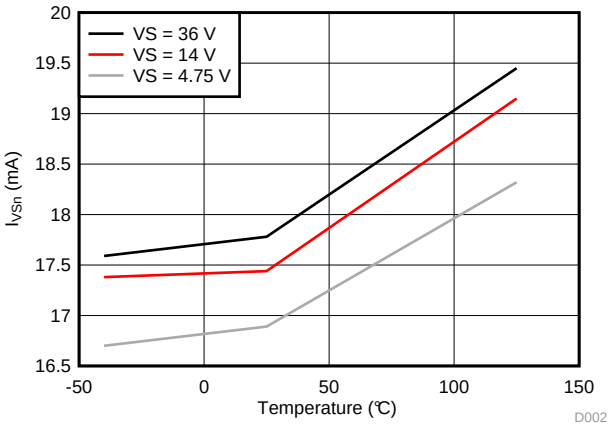


Figure 3. VS Quiescent Current Shutdown

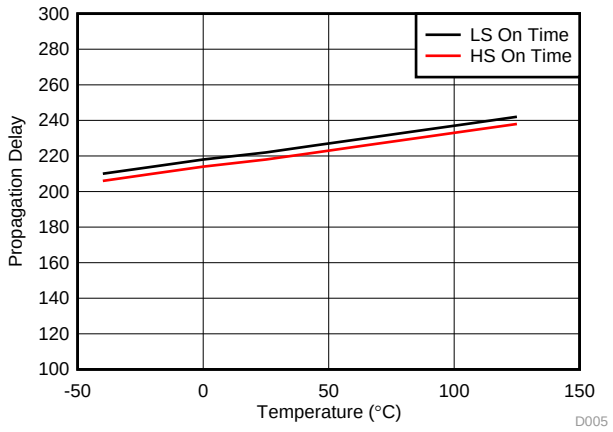


Figure 4. Propagation Delay On Time vs Temperature

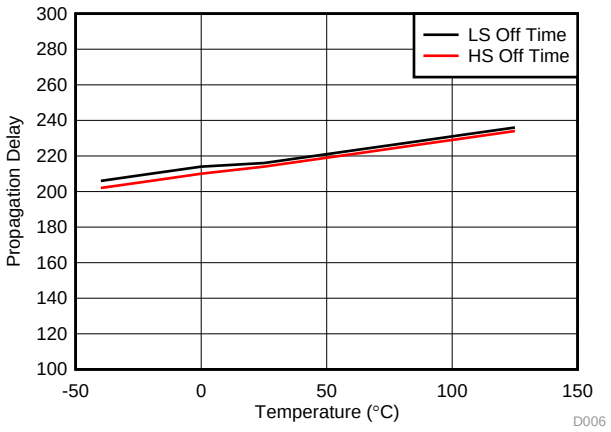


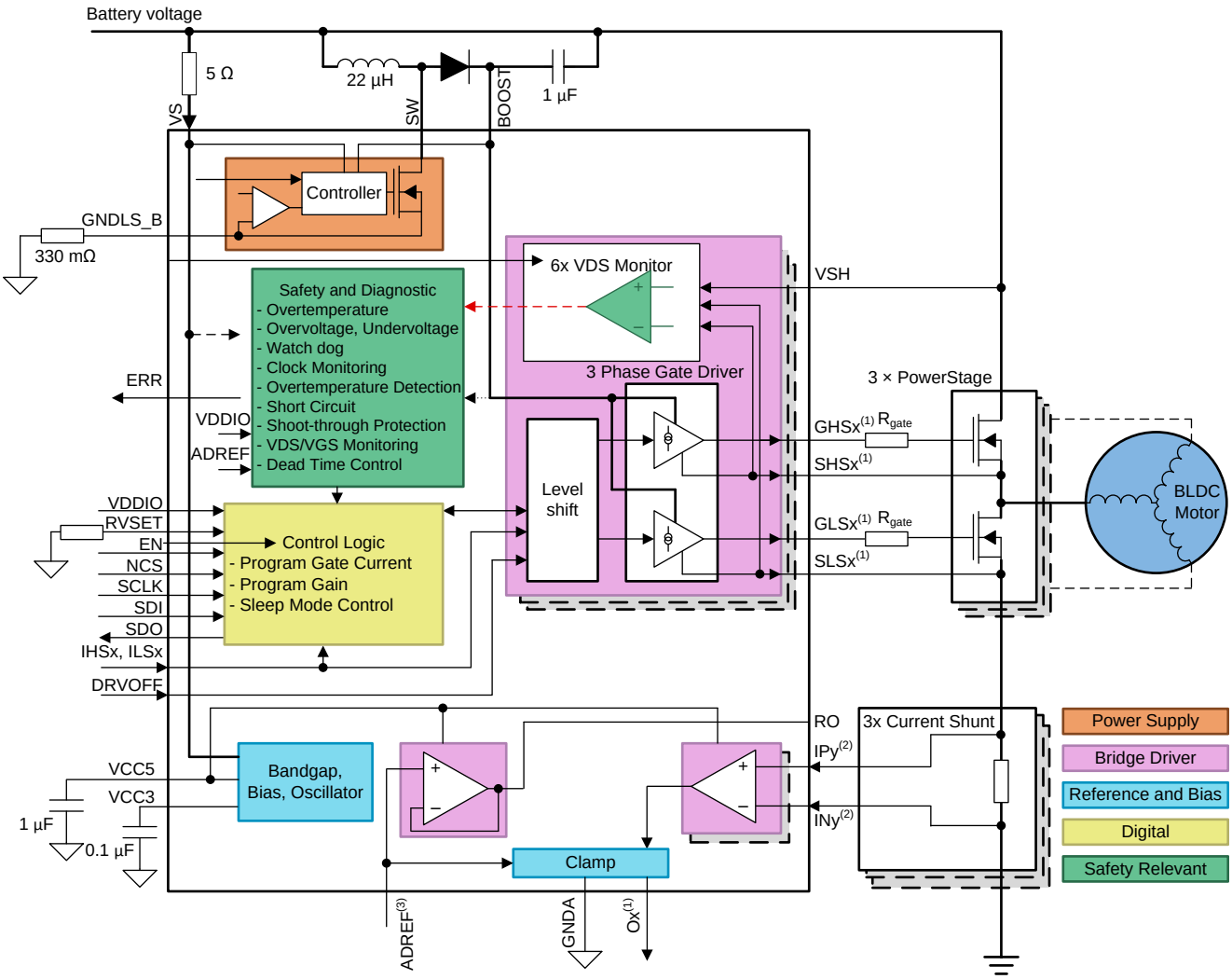
Figure 5. Propagation Delay Off Time vs Temperature

7 Detailed Description

7.1 Overview

The DRV3205-Q1 is designed to control 3-phase brushless DC motors in automotive applications using pulse-width modulation. Three high-side and three low-side gate drivers can be switched individually with low propagation delay. The input logic prevents simultaneous activation of the high-side and low-side driver of the same channel. A configuration and status register can be accessed through a SPI communication interface.

7.2 Functional Block Diagram



(1) x = 1, 2, 3

(2) y = 1, 2, 3

(3) An external reference voltage (VCC5 or VCC3) cannot be used for ADREF voltage.

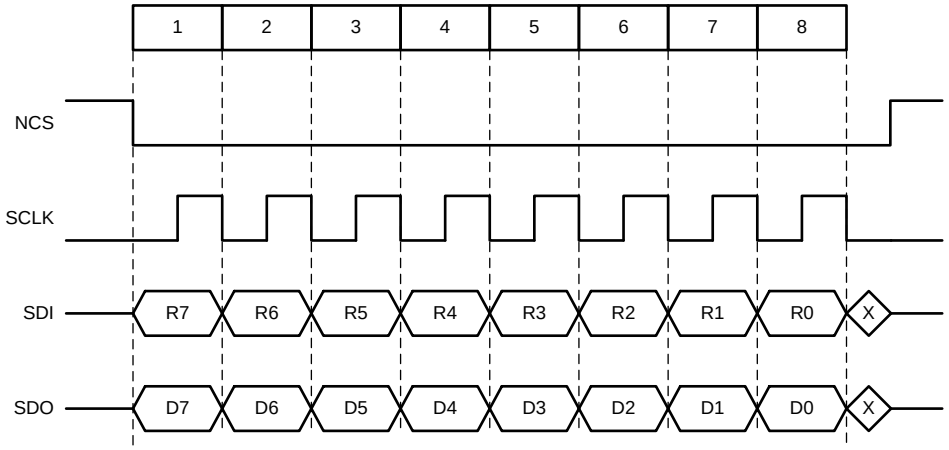
7.3 Programming

7.3.1 SPI

The SPI slave interface is used for serial communication with the external SPI master (external MCU). The SPI communication starts with the NCS falling edge and ends with NCS rising edge. The NCS high level keeps the SPI slave interface in reset state, and the SDO output in tri-state.

7.3.1.1 Address Mode Transfer

The address mode transfer is an 8-bit protocol. Both SPI slave and SPI master transmit the MSB first.



NOTE: SPI master (MCU) and SPI slave (DRV3205-Q1) sample received data on the ~~!– falling~~!~rising SCLK edge and transmit on the ~~!– rising~~!~falling SCLK edge.

Figure 6. Single 8-Bit SPI Frame/Transfer

After the NCS falling edge, the first word of 7 bits are address bits followed by the RW bit. During first address transfer, the device returns the STAT1 register on SDO.

Each complete 8-bit frame will be processed. If NCS goes high before a multiple of 8 bits is transferred, the bits are ignored.

7.3.1.1.1 SPI Address Transfer Phase

Figure 7. SPI Address Transfer Phase Bits

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Function	ADDR6	ADDR5	ADDR4	ADDR3	ADDR2	ADDR1	ADDR0	RW

ADDR [6:0] Register address

RW Read and write access

RW = 0: Read access. The SPI master performs a read access to selected register. During following SPI transfer, the device returns the requested register read value on SDO, and device interprets SDI bits as a next address transfer.

RW = 1: Write access. The master performs a write access on the selected register. The slave updates the register value during next SPI transfer (if followed immediately) and returns the current register value on SDO.

7.3.1.2 SPI Data Transfer Phase

Figure 8. SPI Data Transfer Phase Bits

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Function	DATA7	DATA6	DATA5	DATA4	ADDR3	DATA2	DATA1	DATA0

DATA [7:0] Data value for write access (8-Bit).

Figure 8 shows data value encoding scheme during a write access. Mixing the two access modes (write and read access) during one SPI communication sequence (NCS = 0) is possible. The SPI communication can be terminated after single 8-bit SPI transfer by asserting NCS = 1. Device returns STAT1 register (for the very first SPI transfer after power-up) or current register value that was addressed during SPI Transfer Address Phase.

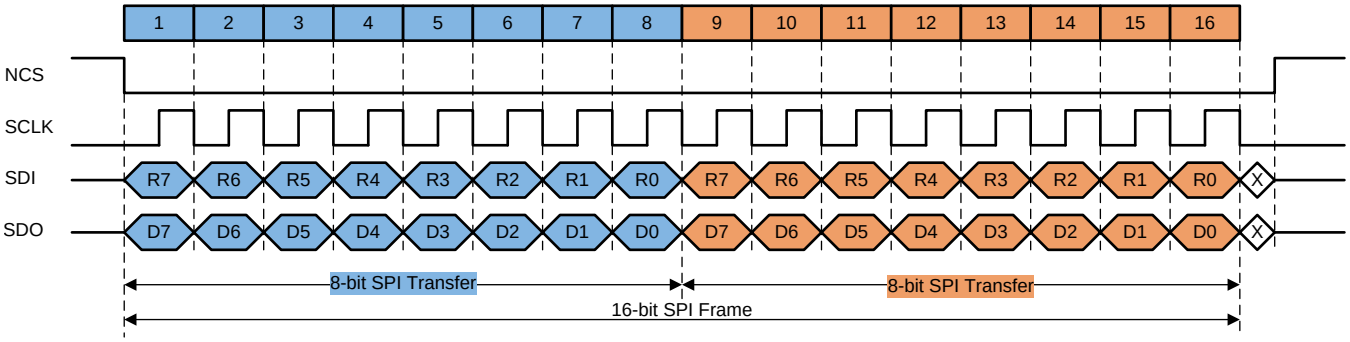
7.3.1.3 Device Data Response

Figure 9. Device Data Response Bits

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Function	REG7	REG6	REG5	REG4	REG3	REG2	REG1	REG0

REG [7:0] Internal register value. All unused bits are set to 0.

Figure 10 shows a complete 16-bit SPI frame. Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, and Figure 16 show the frame examples.



SPI Master (MCU) and SPI slave (DRV32~~!~ 20~~!~05-Q1) sample received data on the rising SCLK edge, and transmit data on the falling SCLK edge

Figure 10. 16-Bit SPI Frame

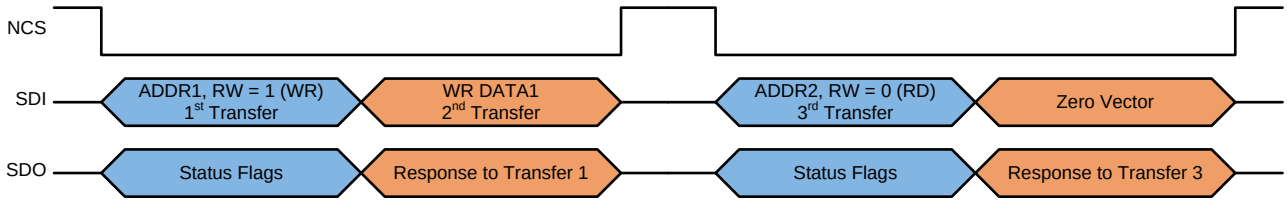


Figure 11. Write Access Followed by Read Access

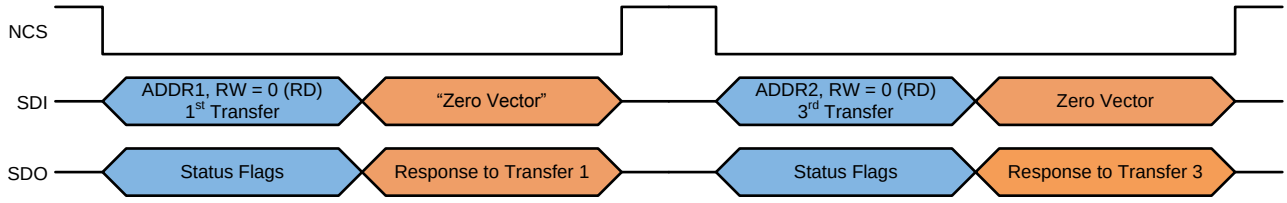


Figure 12. Read Access Followed by Read Access

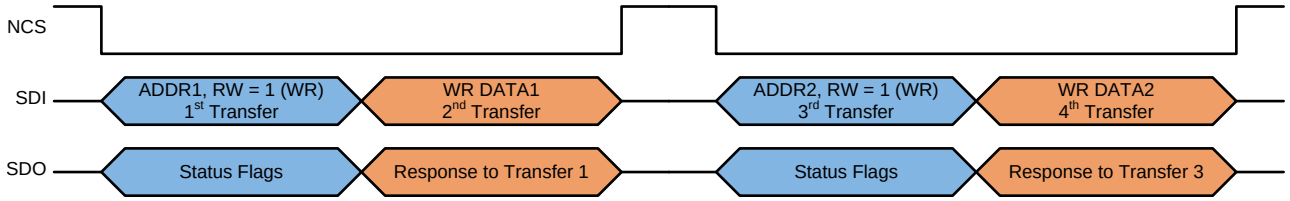


Figure 13. Write Access Followed by Write Access

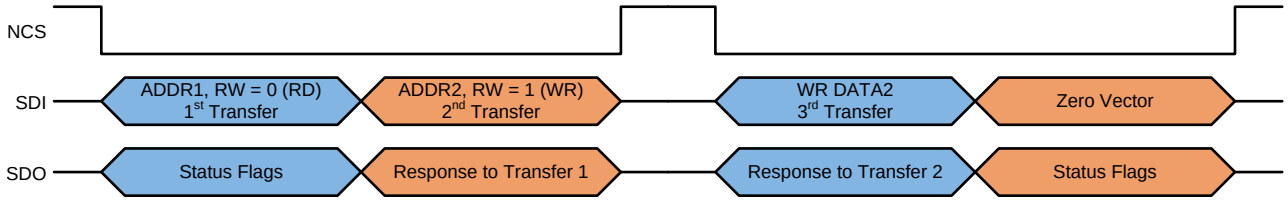


Figure 14. Read Access Followed by Write Access

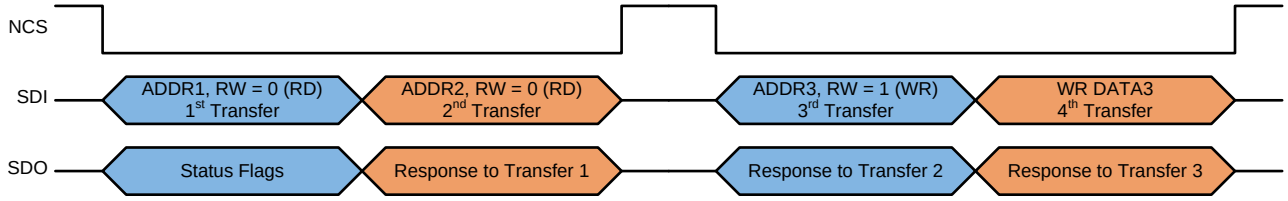


Figure 15. Read Access Followed by Read Access Followed by Write Access

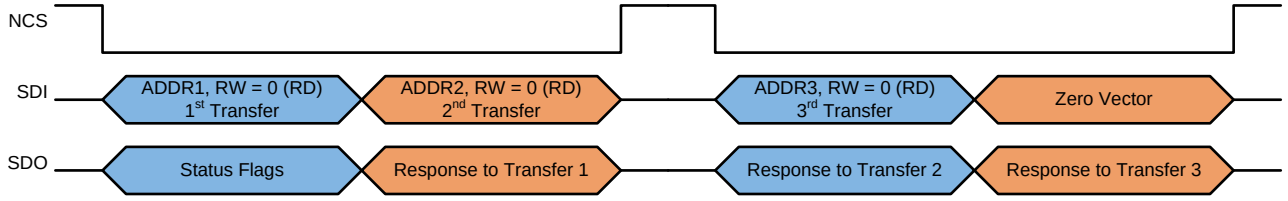


Figure 16. Read Access Followed by Read Access Followed by Read Access

7.4 Register Maps

Table 1. Register Address Map

Address	Name	Reset Value	CRC Check	Access State(1)	Reset Event(2) (bit wide exception)
0×01	Configuration register 0 (CFG0)	8'h3F	Yes	W/R : D, A([6:3]) R : A(7,[2:0], SF	RST1-4
0×02	Configuration register 1 (CFG1)	8'h3F	Yes	W/R: D R: A, SF	RST1-4
0×03	Configuration register 2 (CFG2)	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×04	HS 1/2/3 drive register (CURR0) ON	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×05	LS 1/2/3 drive register (CURR1) ON	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×06	HS 1/2/3 drive register (CURR2) OFF	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×07	LS 1/2/3 drive register (CURR3) OFF	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×08	Safety/error configuration register (SECR1)	8'hC0	Yes	W/R: D R: A, SF	RST1
0×09	Safety function configuration register (SFCR1)	8'h80	Yes	W/R: D R: A, SF	RST1-3
0×0A	Status register 0 (STAT0)	8'h00	No	R: D, A, SF	RST1-4
0×0B	Status register 1 (STAT1)	8'h80	No	R: D, A, SF	RST1-3
0×0C	Status register 2 (STAT2)	8'h00	No	R: D, A, SF	RST1-3
0×0D	Status register 3 (STAT3)	8'h03	No	R: D, A, SF	RST1-3
0×0E	Status register 4 (STAT4)	8'h00	No	R: D, A, SF	RST1-3
0×0F	Status register 5 (STAT5)	8'h03	No	R: D, A, SF	RST1-3 (Bit[4]:RST1)
0×10	Status register 6 (STAT6)	8'h00	No	R: D, A, SF	RST1-3
0×11	Status register 7 (STAT7)	8'h00	No	R: D, A, SF	RST1-4
0×12	Status register 8 (STAT8)	8'h00	No	R: D, A, SF	RST1-4 (Bit[0]:RST1)
0×13	Safety error status (SAFETY_ERR_STAT)	8'h00	No	R: D, A, SF	RST1-3 (Bit[3:1]:RST1)
0×14	Status register 9 (STAT9)	8'h00	No	R: D, A, SF	RST1-3
0×15	Reserved1	8'h00	No	W/R: D, A, SF	RST1-3
0×16	Reserved2	8'h00	No	W/R: D, A, SF	RST1-3
0×1E	SPI transfer write CRC register (SPIWR_CRC)	8'h00	No	W/R: D, A, SF	RST1-3
0×1F	SPI transfer read CRC register (SPIRD_CRC)	8'hFF	No	R: D, A, SF	RST1-3
0×20	SAFETY_CHECK_CTRL register (SFCC1)	8'h01	No	W/R: D R: A, SF	RST1-3
0×21	CRC control register (CRCCTL)	8'h00	No	W/R: D, A R: SF	RST1-3
0×22	CRC calculated (CRCCALC)	N/A	No	W/R: D R: A, SF	RST1-3
0×23	Reserved 3	8'h00	No	W/R: D, A, SF	RST1-3
0×24	HS/LS read back (RB0)	8'h00	No	R: D, A, SF	RST1-3
0×25	HS/LS count control (RB1)	8'h00	No	W/R: D, A R: SF	RST1-4

(1) W/R: Write and Read access possible, W: Write access possible, R: Read access possible
D: DIAGNOSITC STATE, A: ACTIVE STATE, SF: SAFE STATE, SY: STANDBY STATE, R: RESET
(2) RST1: Power up, RST2: System clock error detected by clock monitor RST3: VCC3 UV/OV or from other state to RESET, RST4: LBIST

Register Maps (continued)

Table 1. Register Address Map (continued)

Address	Name	Reset Value	CRC Check	Access State(1)	Reset Event(2) (bit wide exception)
0×26	HS/LS count (RB2)	8'h00	No	R: D, A, SF	RST1-4
0×27	Configuration register 3 (CFG3)	8'hAB	Yes	W/R: D R: A, SF	RST1-4
0×28	Configuration register 4 (CFG4)	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×29	Configuration register 5 (CFG5)	8'hAB	Yes	W/R: D R: A, SF	RST1-3
0×2A	CSM unlock (CSM_UNLOCK1)	8'h00	No	W/R: D R: A, SF	RST1-4
0×2B	CSM unlock (CSM_UNLOCK2)	8'h3F	No	W/R: D R: A, SF	RST1-4
0×2C	RO configuration register 2 (RO_CFG)	8'h00	Yes	W/R: D R: A, SF	RST1-4
0×2D	Safety BIST control register 1 (SAFETY_BIST_CTL1)	8'h00	Yes	W/R: D R: SF, A	RST1-3
0×2E	SPI test register (SPI_TEST)	8'h00	No	W/R: D, A, SF	RST1-4
0×2F	Reserved4	8'h00	No	W/R: D, A, SF	RST1-3
0×30	Safety BIST control register 2 (SAFETY_BIST_CTL2)	8'h00	Yes	W/R: D R: SF, A	RST1-3 (Bit[5]:RST1)
0×31	Watch dog timer configuration register (WDT_WIN1_CFG)	8'h02	Yes	W/R: D R: SF, A	RST1-4
0×32	Watch dog timer configuration register (WDT_WIN2_CFG)	8'h08	Yes	W/R: D R: SF, A	RST1-4
0×33	Watch dog timer TOKEN register (WDT_TOKEN_FDBCK)	8'h04	Yes	W/R: D R: SF, A	RST1
0×34	Watch dog timer TOKEN register (WDT_TOKEN_VALUE)	8'h40	No	R: D, SF, A	RST1-4
0×35	Watch dog timer ANSWER register (WDT_ANSWER)	8'h00	No	W/R: D, A, SF	RST1-4
0×36	Watch dog timer status register (WDT_STATUS)	8'hC0	No	R: D, A, SG	RST1-4
0×37	Watch dog failure detection configuration register (WD_FAIL_CFG)	8'hEC	Yes	W/R: D R: SF, A	RST1-4
0×38	Configuration register 6 (CFG6)	8'h10	Yes	W/R: D R: A, SF	RST1-4
0×39	Configuration register 7 (CFG7)	8'h13	Yes	W/R : D R : A, SF	RST1-4
0×3A	Configuration register 8 (CFG8)	8'h20	Yes	W/R : D R : A, SF	RST1-4
0×3B	Configuration register 9 (CFG9)	8'hFE	Yes	W/R : D R : A, SF	RST1-4

8 Application and Implementation

NOTE

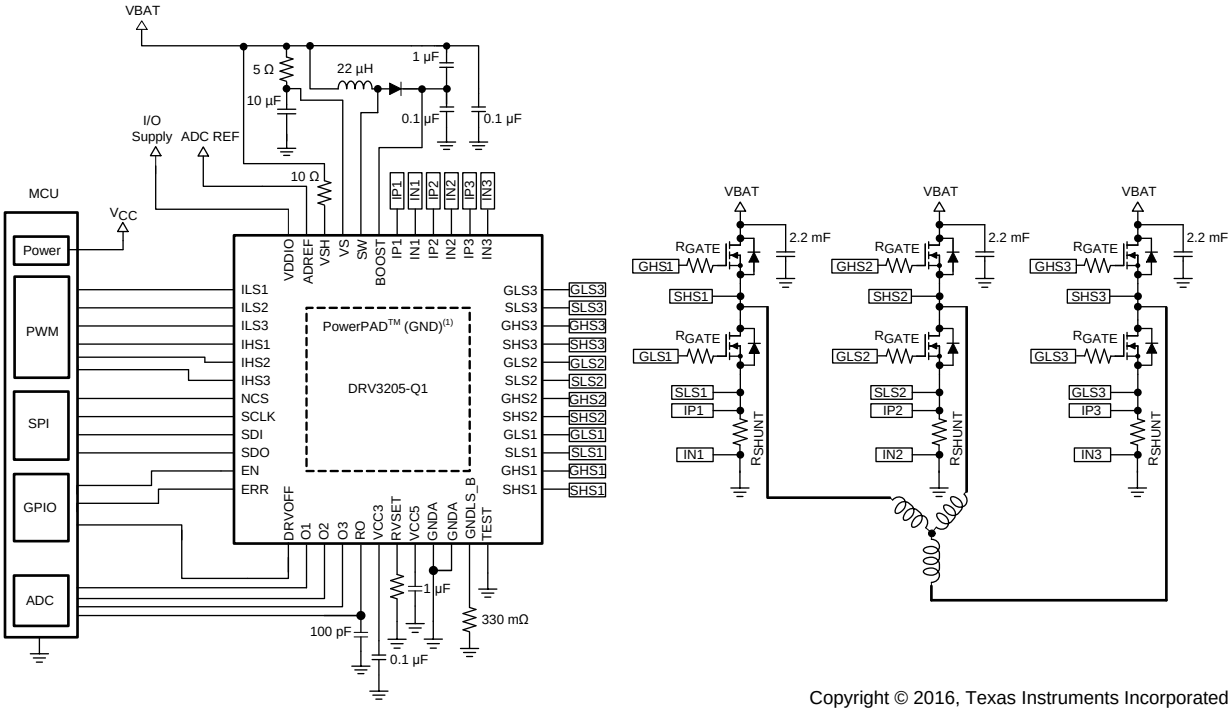
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The DRV3205-Q1 is a predriver for automotive applications featuring three-phase brushless DC-motor control. Because this device has a boost regulator for charging high-side gates, it can handle gate charges of 250 nC. A boost converter allows full control on the power-stages even for a low battery voltage down to 4.75 V.

8.2 Typical Application

8.2.1 Three-Phase Motor Drive-Device for Automotive Application



(1) This schematic of the DRV3205-Q1 48-pin HTQFP does not provide a true representation of physical pin locations.

(2) Use same supply from the TPS6538x as the supply used for the MCU IO.

(3) Resistor not required for reverse protected battery.

(4) L1 = B82442A1223K000 INDUCTOR, SMT, 22 uH, 10%, 480 mA). The maximum inductor current must be more than VGNDLS_B / 330 mΩ.

(5) D1 = SS28 (DIODE, SMT, SCHOTTKY, 80 V, 2 A). A fast recovery diode is recommended.

(6) QxHS, QxLS = IRFS3004PBF (HEXFET, N-CHANNEL, POWER MOSFET, D2PACK)

(7) R_{shunt1} and R_{shunt2} = BVR-Z-R0005 (RES, SMT, 4026, PRECISION POWER, 0.0005 Ω, 1%, 5 W)

(8) R_{gate} = Must be adjust based on system requirement such as EMI, Slew rate, and power

Figure 17. Typical Application Diagram

8.3 System Example

Figure 18 shows a typical system example for an electric power-steering system.

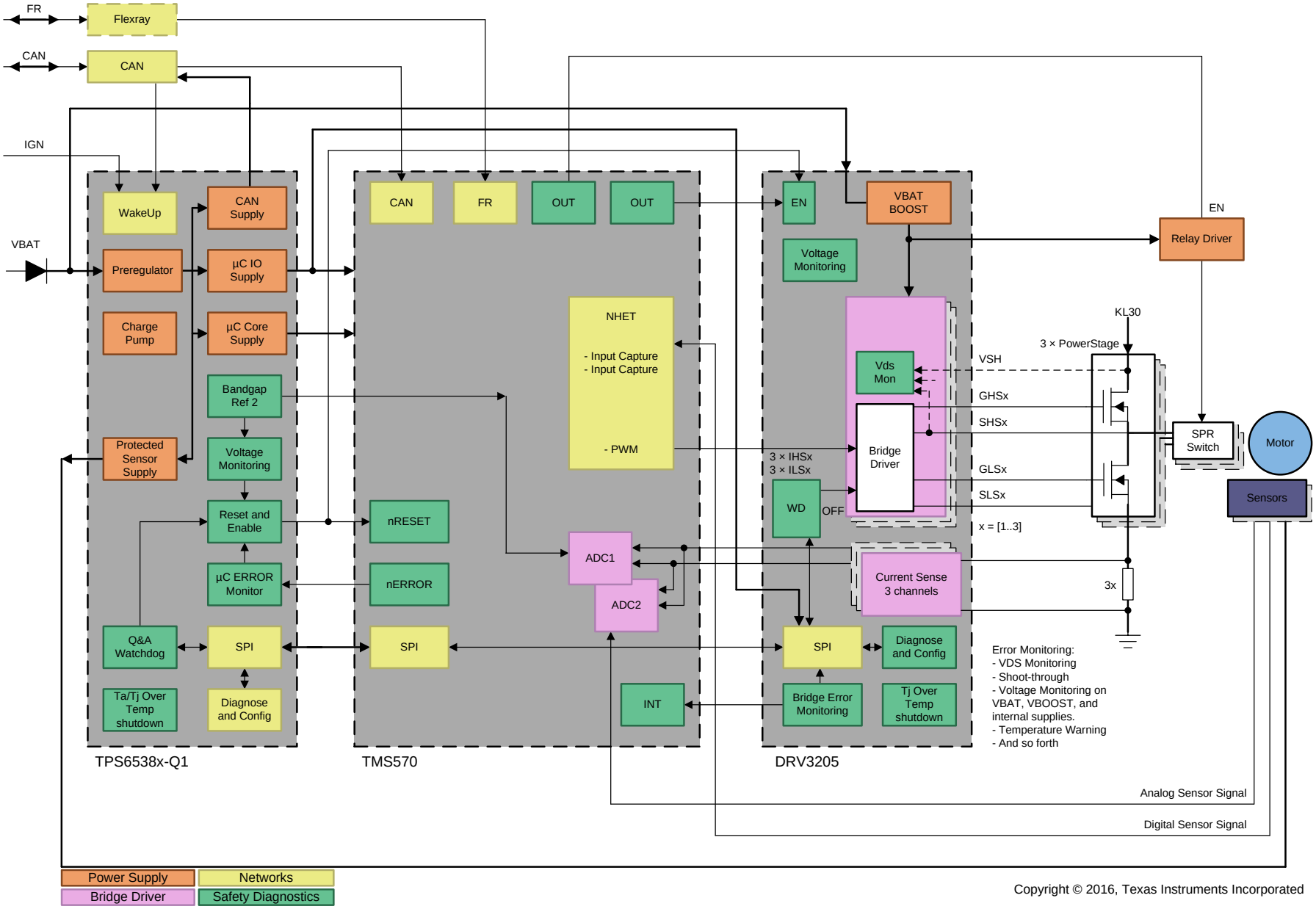


Figure 18. Typical System – Electrical Power Steering Example

9 Power Supply Recommendations

The device is designed to operate from an input voltage supply range of 4.75 V to 40 V. The protection circuit must be placed for protection against reverse supply connection.

10 Layout

10.1 Layout Guidelines

Use the following guidelines when designing a PCB for the DRV3205-Q1:

- In addition to the GND pins, the DRV3205-Q1 makes an electrical connection to GND through the PowerPAD. Always check that the PowerPAD has been properly soldered (see *PowerPAD™ Thermally Enhanced Package* [SLMA002]).
- The VS bypass capacitors should be placed close to the power supply terminals. See the VS box in Figure 19
- Place the VCC5 and VCC5 bypass capacitors close to the corresponding pins with a low impedance path to the ground plane pin (pin 16). See the VCC3 VCC5 bypass box in Figure 19.
- AGND should all be tied to the ground plane through a low impedance trace or copper fill.
- Add stitching vias to reduce the impedance of the GND path from the top to bottom side.
- Try to clear the space around and below the DRV3205-Q1 to allow for better heat spreading from the PowerPAD.
- Route the sense lines, IPx and INx, each with a unique trace, directly to either side of the sense resistor. See the SENSE box in Figure 19.
- Keep the BOOST components close to the device and current loops small. See the BOOST boxes in Figure 19.
- Place the current sense resistors close to the respective low-side FET. See the SENSE box in Figure 19.
- Place the GNDLS_B resistor close to the device pin. See the GNDLS_B box in Figure 19.

10.2 Layout Example

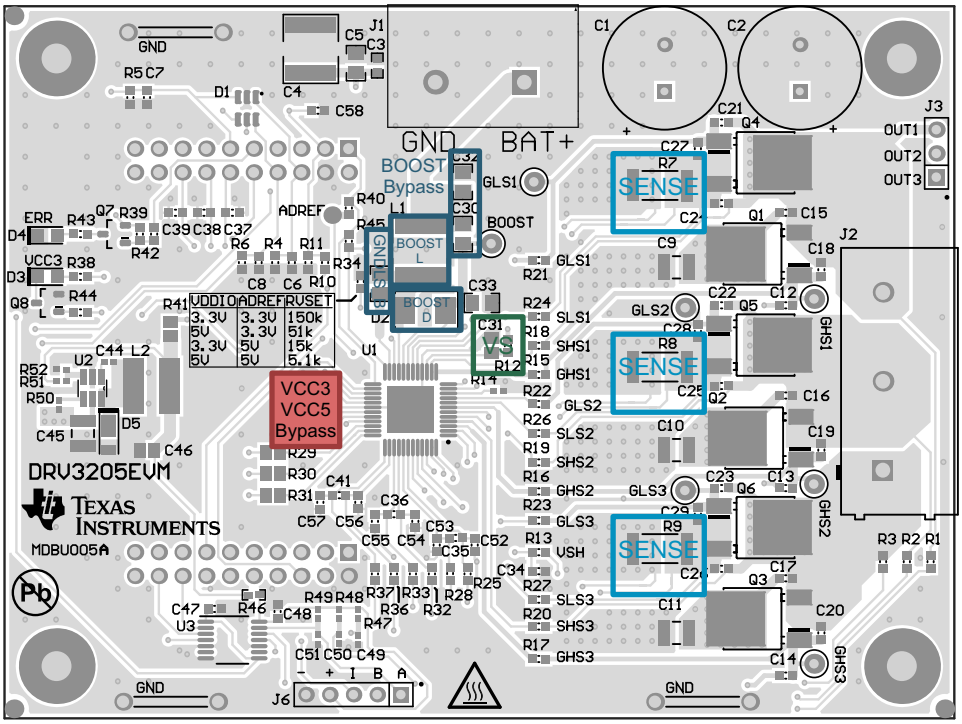


Figure 19. Layout Schematic

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation see the following:

- *DRV3205-Q1 Applications in 24-V Automotive Systems*
- *DRV3205-Q1 Evaluation Module User's Guide*
- *DRV3205-Q1 Negative Voltage Stress on Source Pins*
- *DRV3205-Q1 Safety Manual*
- *Electric Power Steering Design Guide with DRV3205-Q1*
- *PowerPAD™ Thermally Enhanced Package*
- *Protecting Automotive Motor Drive Systems from Reverse Polarity Conditions*
- *Q&A Watchdog Timer Configuration for DRV3205-Q1*
- *TPS653850-Q1 Multirail Power Supply for Microcontrollers in Safety-Relevant Applications*
- *TPS653853-Q1 Multirail Power Supply for Microcontrollers in Safety-Relevant Applications*

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

PowerPAD, E2E are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DRV3205QPHPRQ1	ACTIVE	HTQFP	PHP	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	DRV32205Q	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

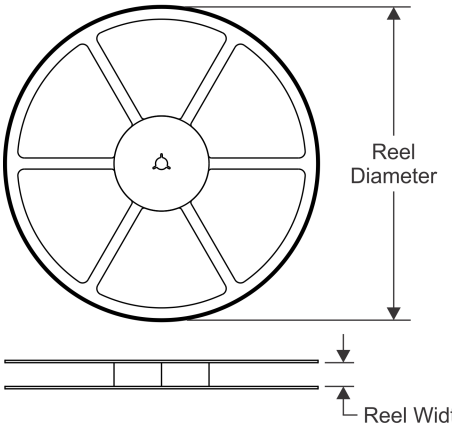
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

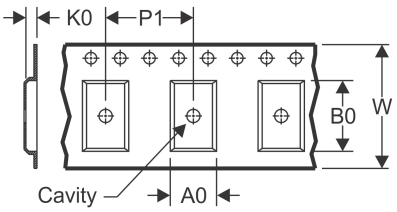
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

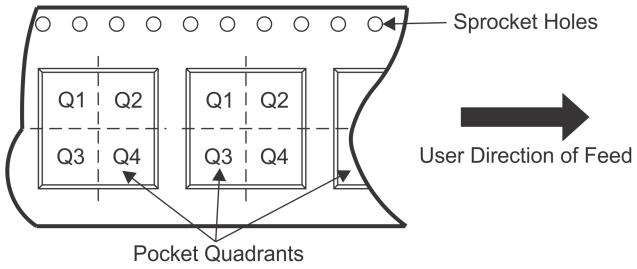


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

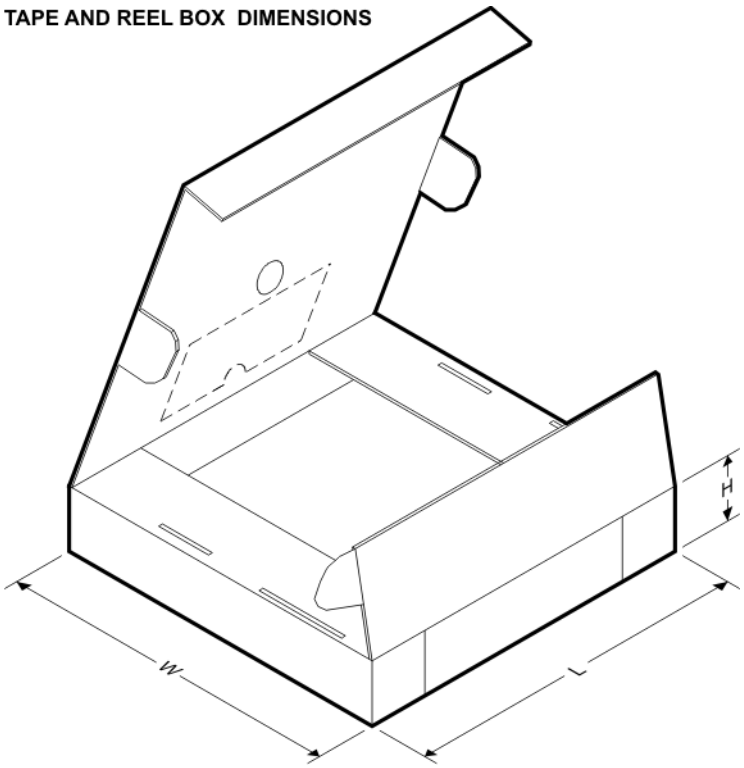
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV3205QPHPRQ1	HTQFP	PHP	48	1000	330.0	16.4	9.6	9.6	1.5	12.0	16.0	Q2

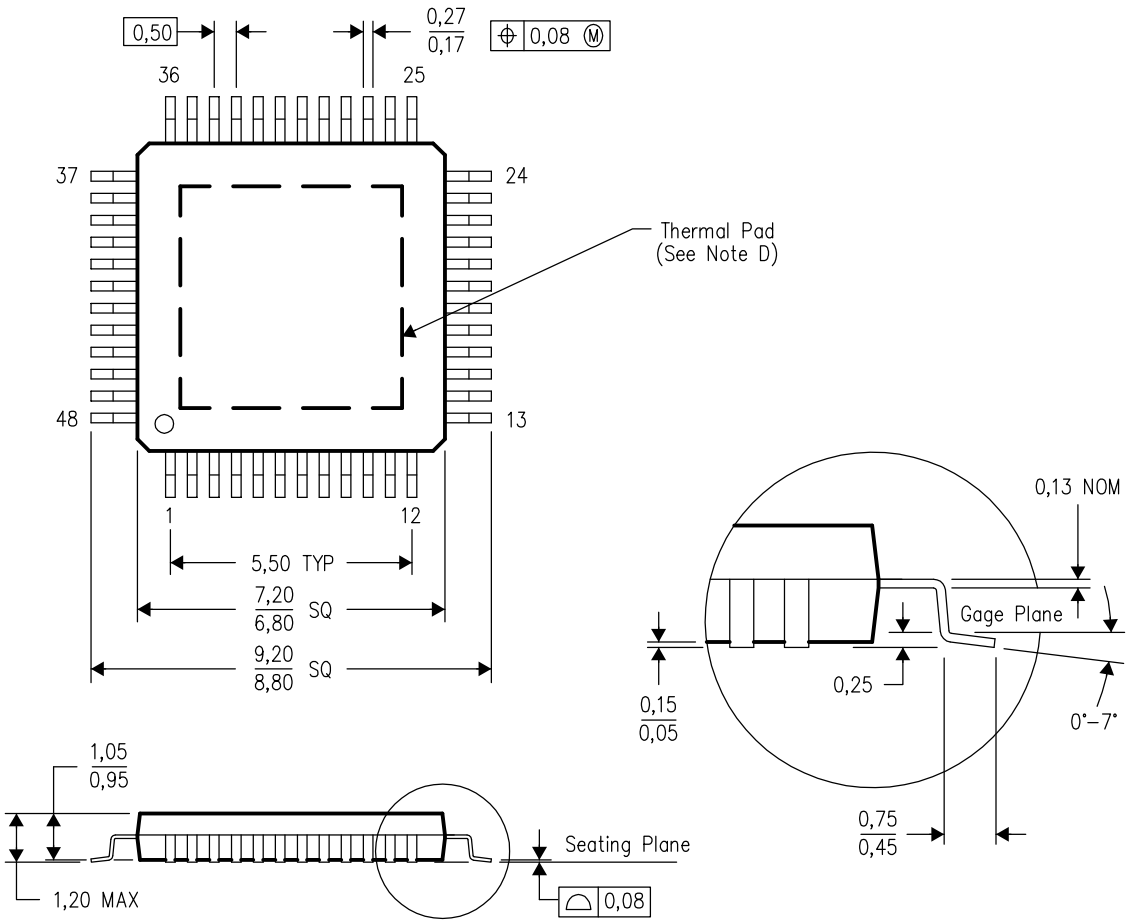
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV3205QPHPRQ1	HTQFP	PHP	48	1000	367.0	367.0	38.0

PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MS–026

PowerPAD is a trademark of Texas Instruments.

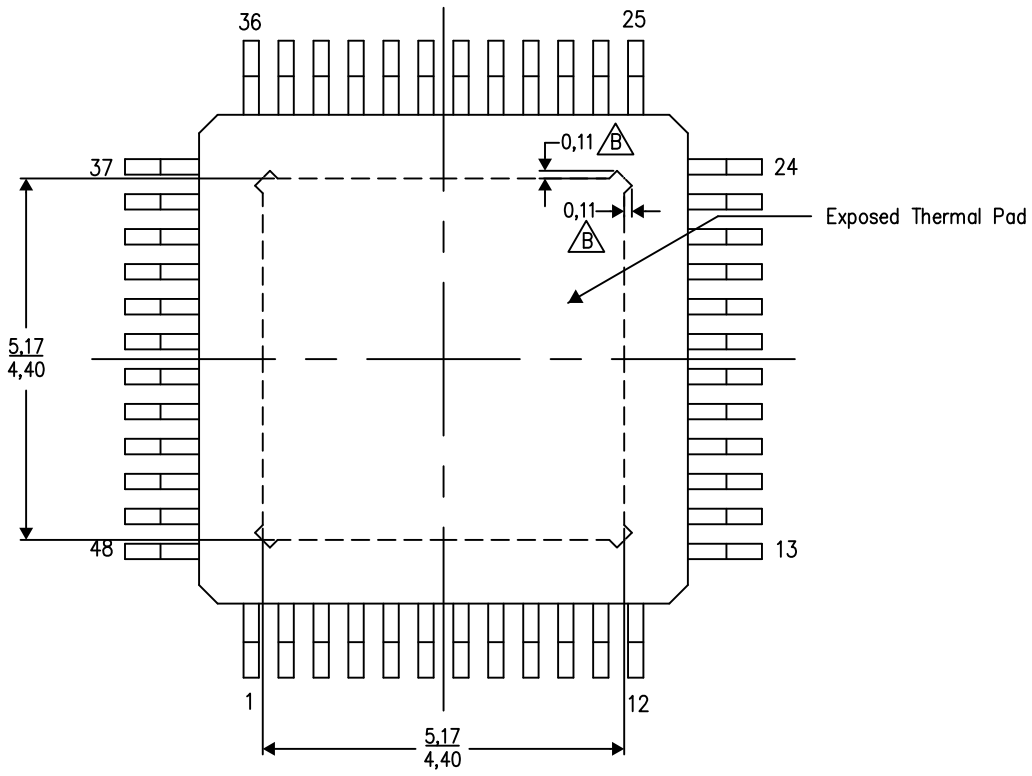
PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

4206329–7/P 03/15

NOTE: A. All linear dimensions are in millimeters

B Tie strap features may not be present.

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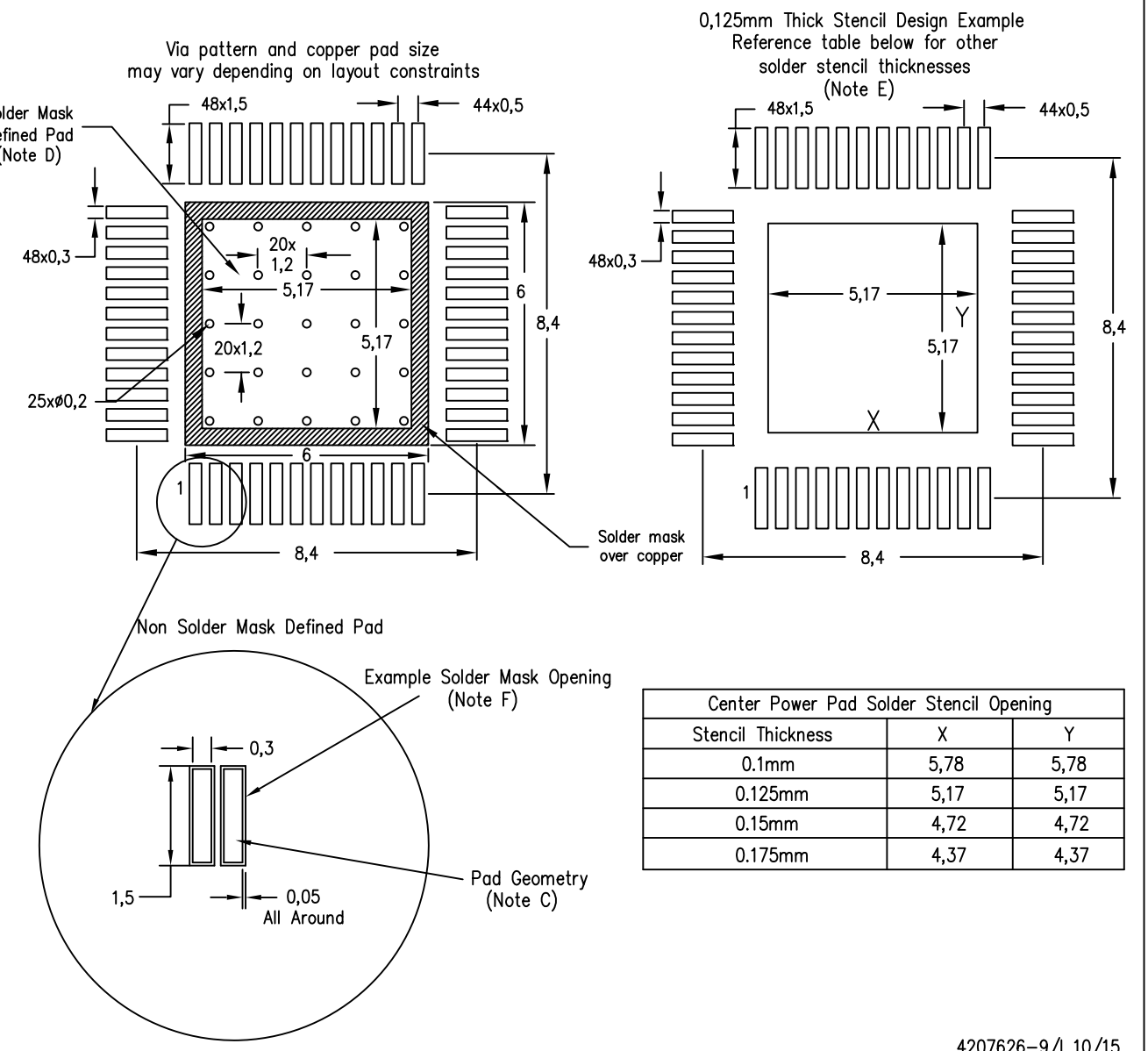
PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



Center Power Pad Solder Stencil Opening		
Stencil Thickness	X	Y
0.1mm	5,78	5,78
0.125mm	5,17	5,17
0.15mm	4,72	4,72
0.175mm	4,37	4,37

4207626–9/I 10/15

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting options for vias placed in the thermal pad.

PowerPAD is a trademark of Texas Instruments

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